

AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph beginning on page 9, line 8, with the following amended paragraph:

Figs. ~~7A and 7B~~ 7 and 8 are views showing a state wherein the SAW filter is accommodated in the package, in which Fig. ~~7A~~ 7 is a plan view and Fig. ~~7B~~ 8 is a sectional view taken along the line VIIB – VIIB of Fig. ~~7A~~ 7.

Please replace the paragraph beginning on page 21, line 15, with the following amended paragraph:

Figs. ~~7A and 7B~~ 7 and 8 are plan and sectional views, respectively, showing a state wherein a SAW filter 100 is accommodated in the package 7 shown in Figs. 6A to 6C. To accommodate the SAW filter 100 in the package 7, first, the SAW filter 100 is set in the groove 78 of the package 7 such that the lower surface of the chip substrate comes into contact with the plate-like portion 80. The comb electrode patterns 11, 12, 13, and 14 and the predetermined pads 71a, 72a, 75a, and 76a are connected to each other through bonding wires 71b, 72b, 75b, and 76b. After that, the upper surface of the package 7 is closed with a plastic member of the like.

Please replace the paragraph beginning on page 23, line 21, with the following amended paragraph:

Furthermore, when the SAW filter 100 is to be accommodated in the package 7 shown in Figs. 6A to 6C, it may be fixed to the package 7 with a conductive adhesive 81, as shown in Fig. ~~7B~~ 8. As shown in Fig. ~~7B~~ 8, the metal plate-like portion 80 is located between

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the SAW filter 100 and package 7. When fixing the SAW filter 100 to the package 7 with the conductive adhesive 81, connection between the SAW filter 100 and plate-like portion 80 becomes firm. Therefore, electrical connection between the SAW filter 100 and the metal plate-like portion 80 can become more reliable.